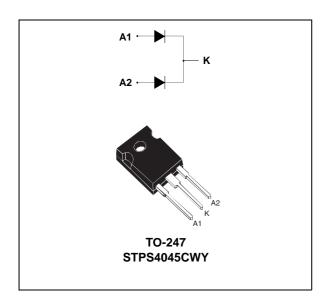
#### **STPS4045C-Y**



#### Automotive power Schottky rectifiers

**Datasheet - production data** 



#### **Features**

- Very small conduction losses
- Negligible switching losses
- Extremely fast switching
- Low thermal resistance
- Avalanche capability specified
- AEC-Q101 qualified

#### **Description**

This dual center tap Schottky rectifier is suited for switch mode power supply and high frequency DC to DC converters.

Packaged in TO-247 this device is intended for use in low voltage, high frequency inverters, free wheeling and polarity protection for automotive applications.

**Table 1. Device summary** 

Symbol	Value
I <sub>F(AV)</sub>	2 x 20 A
$V_{RRM}$	45 V
T <sub>j (max)</sub>	175 °C
V <sub>F (max)</sub>	0.63 V

Characteristics STPS4045C-Y

### 1 Characteristics

Table 2. Absolute ratings (limiting values, per diode)

Symbol	Parame	Value	Unit			
$V_{RRM}$	Repetitive peak reverse voltage	45	V			
I <sub>F(RMS)</sub>	Forward rms current			30	Α	
	Average femueral current	$T_{c} = 150  ^{\circ}\text{C},  \delta = 0.5$	Per diode	20		
IF(AV)	I <sub>F(AV)</sub> Average forward current	$T_{\rm C}$ = 145 °C, $\delta$ = 0.5	Per device	40	Α	
I <sub>FSM</sub>	Surge non repetitive forward current	t <sub>p</sub> = 10 ms sinusoidal	220	Α		
I <sub>RRM</sub>	Repetitive peak reverse current	t <sub>p</sub> = 2 μs square F=1 kl	1	Α		
I <sub>RSM</sub>	Non repetitive peak reverse current $t_p = 100 \ \mu s \ square$			3	Α	
P <sub>ARM</sub>	Repetitive peak avalanche power $t_p = 1 \mu s T_j = 25 °C$			6000	W	
T <sub>stg</sub>	Storage temperature range				°C	
Tj	Operating junction temperature <sup>(1)</sup>			-40 to + 175	°C	
dV/dt	Critical rate of rise reverse voltage			10000	V/µs	

<sup>1.</sup>  $\frac{dPtot}{dT_j} < \frac{1}{Rth(j-a)}$  condition to avoid thermal runaway for a diode on its own heatsink

**Table 3. Thermal resistances** 

Symbol	Parameter	Value	Unit
R <sub>th (j-c)</sub>	Junction to case Per diode Total	1.5 0.8	°C/W
R <sub>th (c)</sub>	Coupling	0.1	

When the diodes 1 and 2 are used simultaneously:

 $\Delta T_j(diode\ 1) = P(diode\ 1)\ x\ R_{th(j\text{-}c)}(Per\ diode)\ +\ P(diode\ 2)\ x\ R_{th(c)}$ 

STPS4045C-Y Characteristics

Symbol	Parameter	Tests conditions		Min.	Тур.	Max.	Unit
I <sub>R</sub> <sup>(1)</sup>	Reverse leakage current	T <sub>j</sub> = 25 °C	\/- <b>-</b> \/	-	-	200	μΑ
IR Weverse leakage curre	Theverse leakage current	T <sub>j</sub> = 125 °C	$V_R = V_{RRM}$	-	11	40	mA
V <sub>F</sub> <sup>(1)</sup> Forward voltage drop	T <sub>j</sub> = 25 °C	I <sub>F</sub> = 20 A	-	-	0.76		
	Forward voltage drop	T <sub>j</sub> = 125 °C	1F = 20 /\	-	0.56	0.63	V
		T <sub>j</sub> = 25 °C	I <sub>F</sub> = 40 A	-	-	0.94	
		T <sub>j</sub> = 125 °C		-	0.7	0.83	

Table 4. Static electrical characteristics (per diode)

To evaluate the conduction losses use the following equation:

$$P = 0.43x I_{F(AV)} + 0.01x I_{F}^{2}_{(RMS)}$$

Figure 1. Average forward power dissipation versus average forward current (per diode)

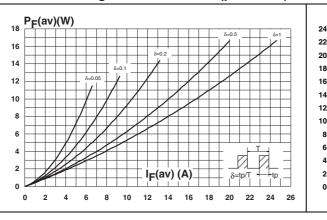


Figure 2. Average forward current versus ambient temperature ( $\delta$  = 0.5 per diode)

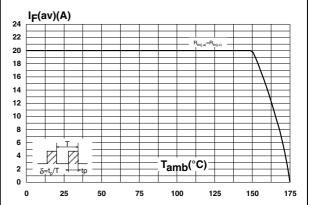
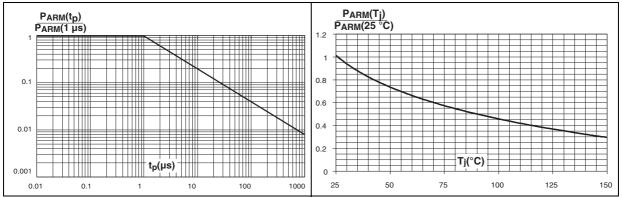


Figure 3. Normalized avalanche power derating versus pulse duration versus junction temperature

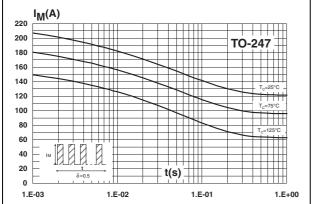


<sup>1.</sup> Pulse test:  $t_p$  = 380  $\mu$ s,  $\delta$  < 2%

Characteristics STPS4045C-Y

Figure 5. Non repetitive surge peak forward current versus overload duration (maximum values, per diode)

Figure 6. Relative variation of thermal impedance junction to case versus pulse duration



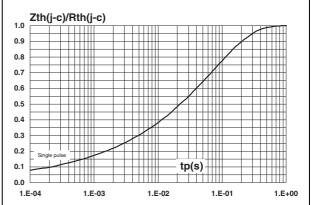
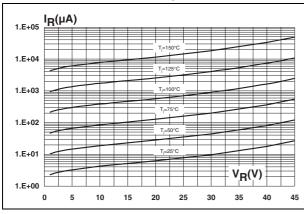


Figure 7. Reverse leakage current versus reverse voltage applied (typical values, per diode)

Figure 8. Junction capacitance versus reverse voltage applied (typical values, per diode)



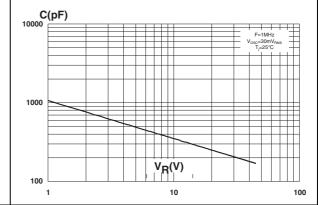
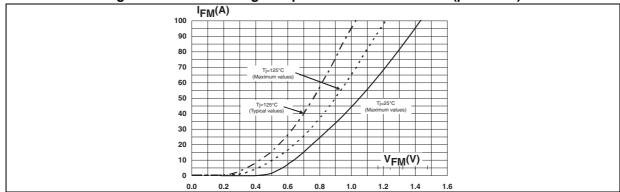


Figure 9. Forward voltage drop versus forward current (per diode)



#### 2 Package information

- Epoxy meets UL94,V0
- Cooling method: by conduction (C)
- Recommended torque values: 0.9 to 1.2 N·m

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK<sup>®</sup> packages, depending on their level of environmental compliance. ECOPACK<sup>®</sup> specifications, grade definitions and product status are available at: www.st.com. ECOPACK<sup>®</sup> is an ST trademark.

BACK VIEW

Figure 10. TO-247 dimension definitions

Package information STPS4045C-Y

Table 5. TO-247 dimension values

	Dimensions						
Ref.	Millimeters			Inches			
	Min.	Тур.	Max.	Min.	Тур	Max.	
А	4.85		5.15	0.191		0.203	
A1	2.20		2.60	0.086		0.102	
b	1.00		1.40	0.039		0.055	
b1	2.00		2.40	0.078		0.094	
b2	3.00		3.40	0.118		0.133	
С	0.40		0.80	0.015		0.031	
D <sup>(1)</sup>	19.85		20.15	0.781		0.793	
E	15.45		15.75	0.608		0.620	
е	5.30	5.45	5.60	0.209	0.215	0.220	
L	14.20		14.80	0.559		0.582	
L1	3.70		4.30	0.145		0.169	
L2	18.50 typ.			0.728 typ.			
ØP <sup>(2)</sup>	3.55		3.65	0.139		0.143	
ØR	4.50		5.50	0.177		0.217	
S	5.30	5.50	5.70	0.209	0.216	0.224	

<sup>1.</sup> Dimension D plus gate protrusion does not exceed 20.5 mm

<sup>2.</sup> Resin thickness around the mounting hole is not less than 0.9  $\mbox{mm}$ 

# 3 Ordering information

**Table 6. Ordering information** 

Order code	Marking	Package	Weight	Base qty.	Delivery mode
STPS4045CWY	STPS4045CWY	TO-247	4.46 g	30	Tube

## 4 Revision history

**Table 7. Document revision history** 

Date	Revision	Changes
17-Dec-2013	1	First issue.

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8/8 DocID17952 Rev 1

